

In the Claims:

Please cancel claims 5 and 12, amend claims 3, 6 and 10, and add new claim 19, as follows.

1. (Original) A semiconductor device, comprising:

a base carrier having a top side and a bottom side, the top side having a central area for receiving an integrated circuit die and a peripheral area;

an extended adhesive material layer disposed on the top side of the base carrier, the adhesive material layer covering the central area and a large portion of the peripheral area of the base carrier top surface; and

an integrated circuit die attached to the base carrier with the adhesive material layer at the central area.
2. (Original) The semiconductor device of claim 1, wherein the base carrier comprises a paddle.
3. (Amended) The semiconductor device of claim 2, further comprising a leadframe electrically connected to [which bonding pads of] the integrated circuit [device] die [are electrically connected].
4. (Original) The semiconductor device of claim 3, further comprising an encapsulant surrounding the base carrier, the integrated circuit die and at least a portion of the leadframe.
5. Cancelled.

6. (Amended) A semiconductor device, comprising:

a base carrier having a top side and a bottom side, the top side having a central area for receiving an integrated circuit die and a peripheral area;

an extended adhesive material layer disposed on the top side of the base carrier, wherein the adhesive material layer is dispensed on the top side of the base carrier in an "X" shaped pattern, the "X" shaped pattern including two bisecting lines, wherein the two bisecting lines extend beyond the central area and into the peripheral area of the base carrier top surface; and

an integrated circuit die attached to the base carrier with the adhesive material layer at the central area.

7. (Original) The semiconductor device of claim 6, wherein the "X" shaped pattern of adhesive material further includes a first line extending from a middle part of the peripheral area of a first side of the base carrier to a middle part of the peripheral area of a second, opposing side of the base carrier such that the adhesive material layer forms a six pointed star.

8. (Original) The semiconductor device of claim 7, wherein the "X" shaped pattern of adhesive material further includes a second line extending from a middle part of the peripheral area of a third side of the base carrier to a middle part of the peripheral area of a fourth, opposing side of the base carrier such that the adhesive material layer forms an eight pointed star.

9. (Original) The semiconductor device of claim 6, wherein the base carrier comprises a paddle.

10. (Amended) The semiconductor device of claim 9, further comprising a leadframe electrically connected to [which bonding pads of] the integrated circuit [device] die [are electrically connected].

11. (Original) The semiconductor device of claim 10, further comprising an encapsulant surrounding the base carrier, the integrated circuit die and at least a portion of the leadframe.

12. Cancelled.

13-18. Withdrawn

19. (New) An improved method of attaching an integrated circuit die to a base carrier, wherein a top side of the base carrier has a central area for receiving the die and a peripheral area surrounding the central area, the improvement comprising:

an extended adhesive material layer, disposed on the top side of the base carrier and covering the central area and a large portion of the peripheral area, for attaching the die to the base carrier.